

# MJ P-Channel Enhancement Mode Power MOSFET

## Description

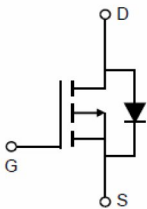
The MJ60P02Y uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is well suited for use as a load switch or in PWM applications.

### General Features

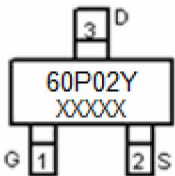
- ◆ V<sub>DS</sub> =-60V,I<sub>D</sub> =-2A
- ◆ R<sub>DS(ON)</sub> <160mΩ @ V<sub>GS</sub> =-10V
- ◆ R<sub>DS(ON)</sub> <200mΩ @ V<sub>GS</sub> =-4.5V
- ◆ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Excellent package for good heat dissipation

### Application

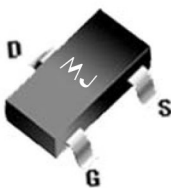
- ◆ Load switch
- ◆ PWM application



Schematic diagram



Marking and pin assignment



SOT-23-3L top view

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
60P02Y	MJ60P02Y	SOT23-3L	Ø180mm	8 mm	3000 units

## Absolute Maximum Ratings (T<sub>c</sub> =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-60	V
Gate-Source Voltage	V <sub>DS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	-2	A
Pulsed Drain Current <sup>(Note 1)</sup>	I <sub>DM</sub>	-8	A
Maximum Power Dissipation	P <sub>D</sub>	1.7	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	°C

## Thermal Characteristic

Thermal Resistance,Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJA</sub>	73.5	°C/W
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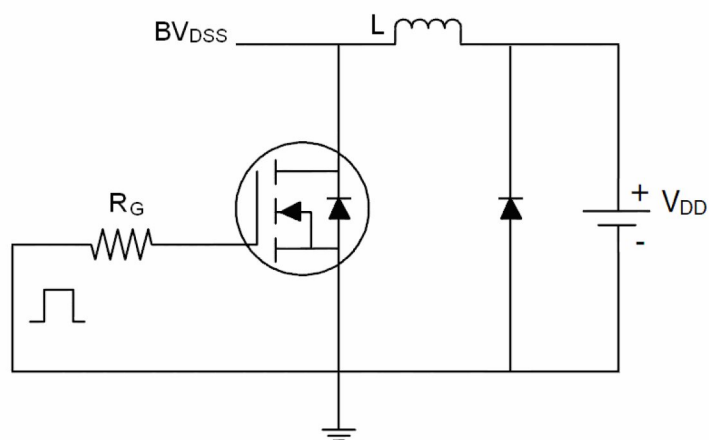
Electrical Characteristics (T<sub>A</sub> =25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =±20V,V <sub>GS</sub> =0V	-	-	±100	nA
On Characteristics <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	-1.4	-2.0	-2.6	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2A	-	140	160	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A	-	160	200	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-2A	-	3	-	S
Dynamic Characteristics <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V, F=1.0MHz	-	452	-	PF
Output Capacitance	C <sub>OSS</sub>		-	27.8	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	21.5	-	PF
Switching Characteristics <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30V, ,R <sub>L</sub> =-2Ω V <sub>GS</sub> =-10V,R <sub>GEN</sub> =3Ω	-	40	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	35	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	15	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-30V,I <sub>D</sub> =-2A, V <sub>GS</sub> =-10V	-	9.0	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	1.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-2A	-		-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	-2	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> =- 2A di/dt = -100A/μs <sup>(Note3)</sup>	-	25		nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	31		nC

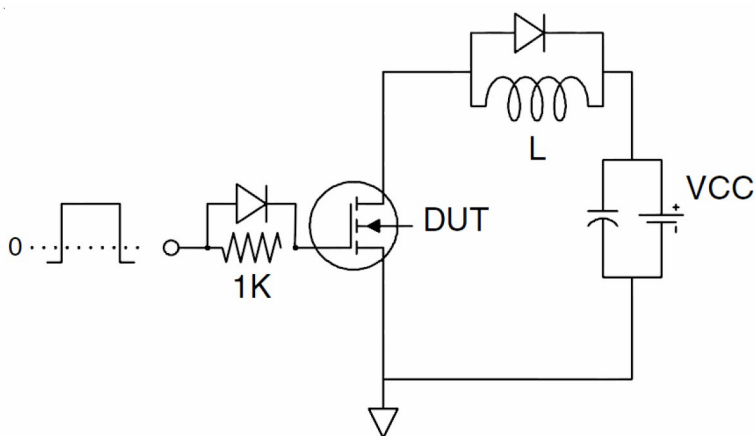
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production

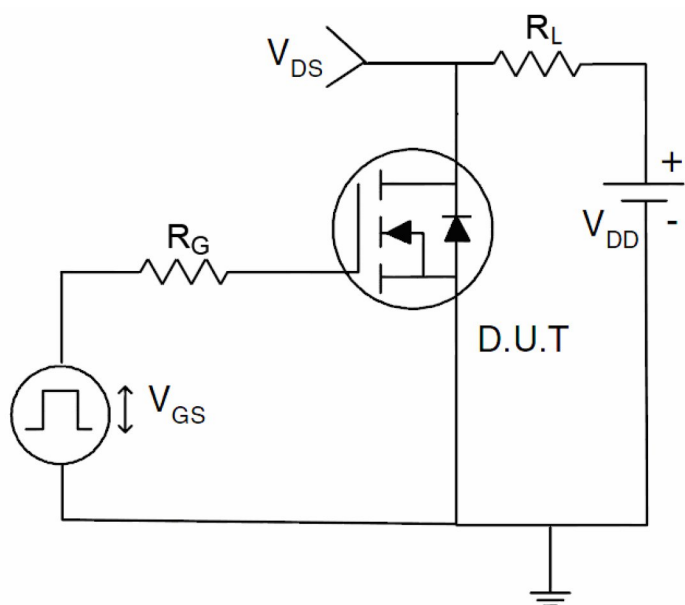
## Test Circuit



EAS test Circuit



Gate charge test Circuit



Switch Time Test Circuit

## Typical Electrical and Thermal Characteristics (Curves)

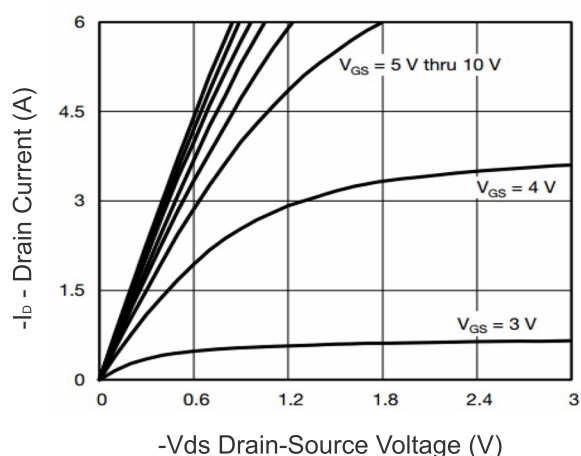


Figure 1 Output Characteristics

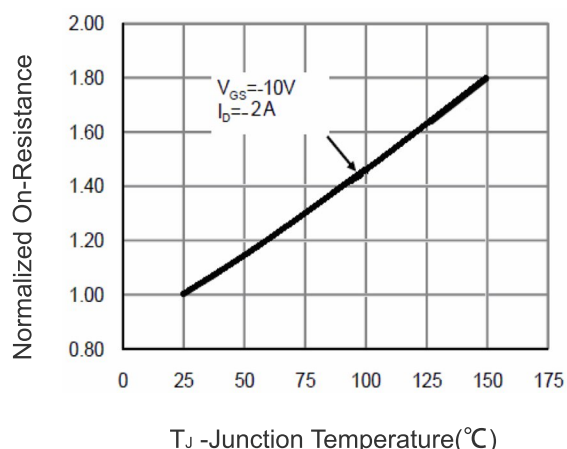


Figure 4  $R_{DS(on)}$ -Junction Temperature

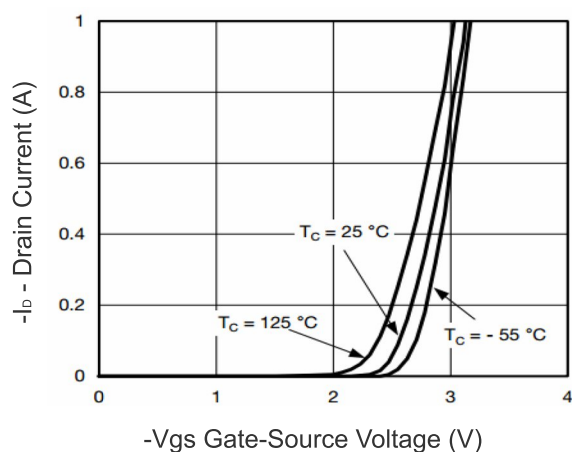


Figure 2 Transfer Characteristics

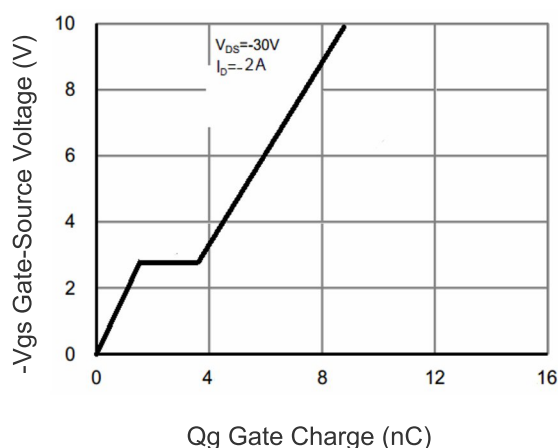


Figure 5 Gate Charge

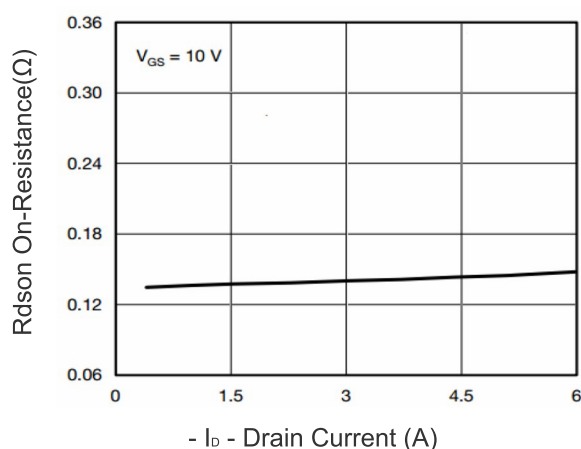


Figure 3  $R_{DS(on)}$ - Drain Current

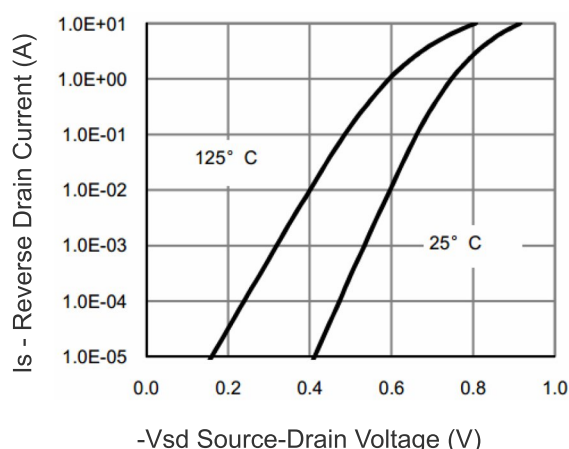


Figure 6 Source- Drain Diode Forward

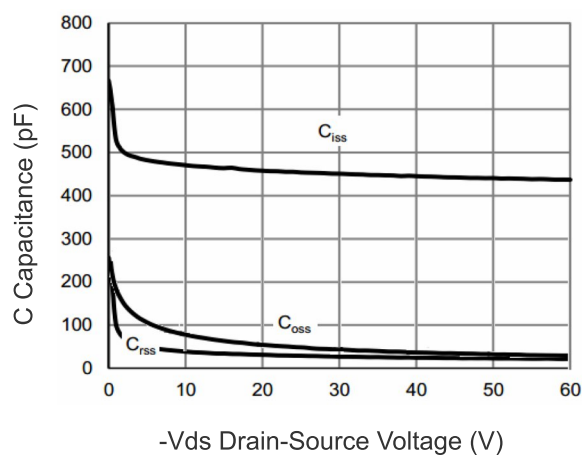


Figure 7 Capacitance vs Vds

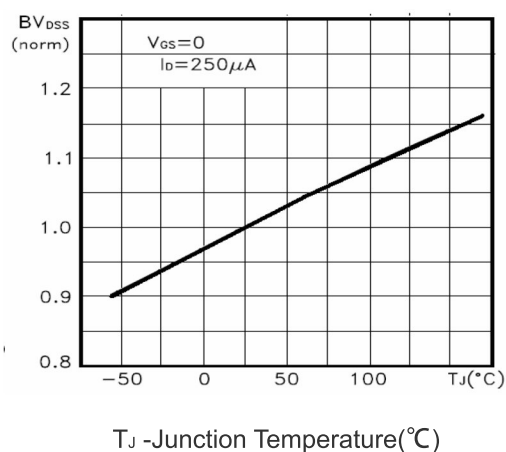
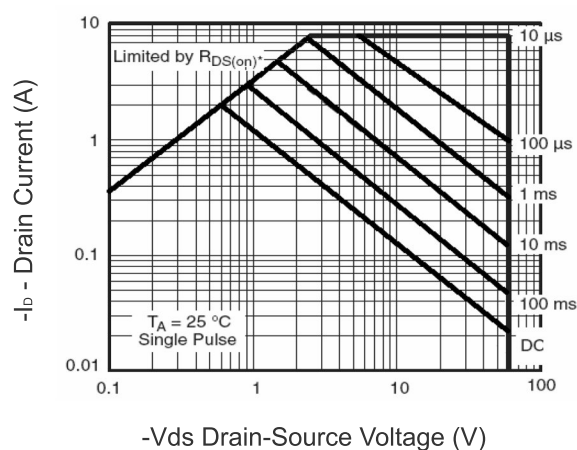

Figure 9  $BV_{DSS}$  vs Junction Temperature


Figure 8 Safe Operation Area

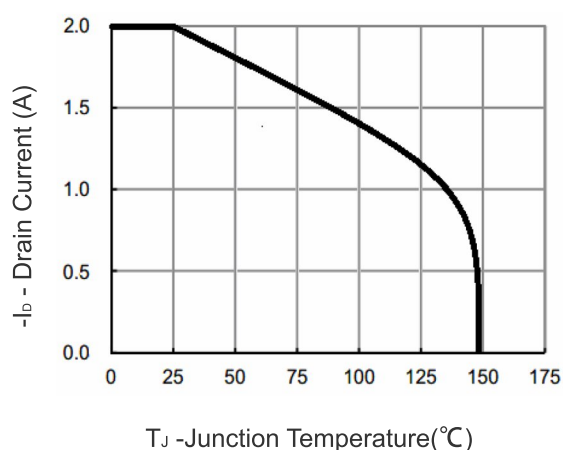
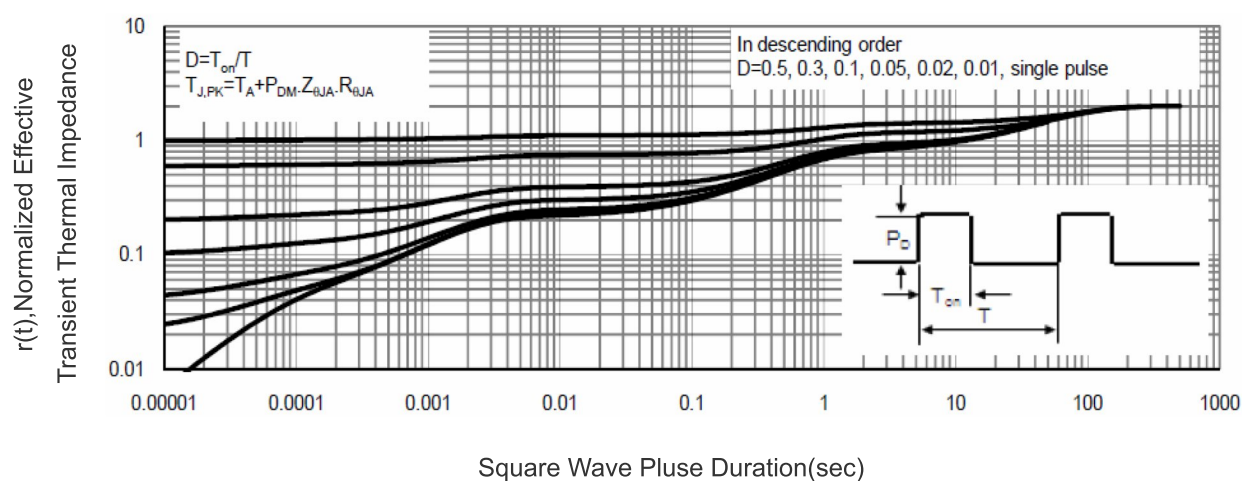

Figure 10  $I_D$  Current De-rating


Figure 11 Normalized Maximum Transient Thermal Impedance



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